



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50R380CE		<b>Issued</b>		25. January 2018			
<b>MA#</b>		MA001504450							
<b>Package</b>		PG-TO252-3-344		<b>Weight*</b>		323.79 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.808	1.18	1.18	11761	11761	
leadframe	non noble metal	iron	7439-89-6	0.144	0.04		445		
	inorganic material	phosphorus	7723-14-0	0.043	0.01		133		
	non noble metal	copper	7440-50-8	143.904	44.46	44.51	444441	445019	
wire	non noble metal	aluminium	7429-90-5	4.434	1.37	1.37	13695	13695	
encapsulation	organic material	carbon black	1333-86-4	0.657	0.20		2028		
	plastics	epoxy resin	-	17.726	5.47		54744		
	inorganic material	silicondioxide	60676-86-0	112.918	34.87	40.54	348742	405514	
leadfinish	non noble metal	tin	7440-31-5	3.834	1.18	1.18	11840	11840	
solder	noble metal	silver	7440-22-4	0.082	0.03		253		
	non noble metal	tin	7440-31-5	0.066	0.02		203		
	non noble metal	lead	7439-92-1	3.134	0.97	1.02	9680	10136	
heatspreader	non noble metal	iron	7439-89-6	0.033	0.01		102		
	inorganic material	phosphorus	7723-14-0	0.010	0.00		31		
	non noble metal	copper	7440-50-8	32.995	10.19	10.20	101902	102035	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com